

BLF6G15L-40RN; BLF6G15LS-40RN

Power LDMOS transistor

Rev. 1 — 27 October 2011

Objective data sheet

1. Product profile

1.1 General description

40 W LDMOS power transistor for base station applications at frequencies from 1450 MHz to 1550 MHz.

Table 1. Typical performance

Typical RF performance at $T_{case} = 25\text{ °C}$ in a class-AB production test circuit.

Test signal	f (MHz)	V_{DS} (V)	$P_{L(AV)}$ (W)	G_p (dB)	η_D (%)	ACPR (dBc)
2-carrier W-CDMA	1476 to 1511	28	2.5	21.5	13.0	-47 ^[1]

[1] Test signal: 3GPP test model 1; 64 DPCH; PAR = 7.5 dB at probability of 0.01 % on CCDF carrier; carrier spacing 5 MHz.

1.2 Features and benefits

- Typical 2-carrier W-CDMA performance at frequencies of 1476 MHz and 1511 MHz, a supply voltage of 28 V and an I_{DQ} of 370 mA:
 - ◆ Average output power = 2.5 W
 - ◆ Power gain = 21.5 dB
 - ◆ Efficiency = 13.0 %
 - ◆ ACPR = -47 dBc
- Easy power control
- Integrated ESD protection
- Enhanced ruggedness
- High efficiency
- Excellent thermal stability
- Designed for broadband operation (1450 MHz to 1550 MHz)
- Internally matched for ease of use
- Compliant to Restriction of Hazardous Substances (RoHS) Directive 2002/95/EC.

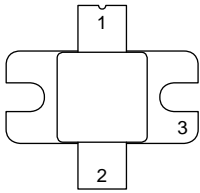
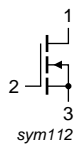
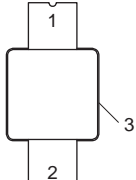
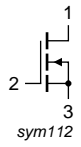
1.3 Applications

- RF power amplifiers for W-CDMA base stations and multi carrier applications in the 1450 MHz to 1550 MHz frequency range



2. Pinning information

Table 2. Pinning

Pin	Description	Simplified outline	Graphic symbol
BLF6G15L-40RN (SOT1135A)			
1	drain		 sym112
2	gate		
3	source [1]		
BLF6G15LS-40RN (SOT1135B)			
1	drain		 sym112
2	gate		
3	source [1]		

[1] Connected to flange.

3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BLF6G15L-40RN	-	flanged ceramic package; 2 mounting holes; 2 leads	SOT1135A
BLF6G15LS-40RN	-	earless flanged ceramic package; 2 leads	SOT1135B

4. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DS}	drain-source voltage		-	65	V
V_{GS}	gate-source voltage		-0.5	+11	V
I_D	drain current		-	11	A
T_{stg}	storage temperature		-65	+150	°C
T_j	junction temperature		-	200	°C

5. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Typ	Unit
$R_{th(j-case)}$	thermal resistance from junction to case	$T_{case} = 80\text{ °C}; P_L = 2.5\text{ W (CW)}$	1.6	K/W

6. Characteristics

Table 6. Characteristics

$T_j = 25\text{ °C}$ per section; unless otherwise specified

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{(BR)DSS}$	drain-source breakdown voltage	$V_{GS} = 0\text{ V}; I_D = 0.59\text{ mA}$	65	-	-	V
$V_{GS(th)}$	gate-source threshold voltage	$V_{DS} = 10\text{ V}; I_D = 59\text{ mA}$	1.4	1.9	2.4	V
I_{DSS}	drain leakage current	$V_{GS} = 0\text{ V}; V_{DS} = 28\text{ V}$	-	-	1.4	μA
I_{DSX}	drain cut-off current	$V_{GS} = V_{GS(th)} + 3.75\text{ V}; V_{DS} = 10\text{ V}$	-	10	-	A
I_{GSS}	gate leakage current	$V_{GS} = 11\text{ V}; V_{DS} = 0\text{ V}$	-	-	140	nA
g_{fs}	forward transconductance	$V_{DS} = 10\text{ V}; I_D = 2.9\text{ A}$	-	4.3	-	S
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = V_{GS(th)} + 3.75\text{ V}; I_D = 2.06\text{ A}$	-	0.25	-	Ω

7. Application information

Table 7. 2-carrier W-CDMA RF performance

Class-AB production test circuit; PAR 7.5 dB at 0.01 % probability on CCDF; 3GPP test model 1; 64 DPCH; $f_1 = 1473.4\text{ MHz}; f_2 = 1478.4\text{ MHz}; f_3 = 1508.4\text{ MHz}; f_4 = 1513.4\text{ MHz}$; RF performance at $V_{DS} = 28\text{ V}; I_{Dq} = 370\text{ mA}; T_{case} = 25\text{ °C}$; unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$P_{L(AV)}$	average output power		-	2.5	-	W
G_p	power gain	$P_{L(AV)} = 2.5\text{ W}$	<td>	21.5	-	dB
RL_{in}	input return loss	$P_{L(AV)} = 2.5\text{ W}$	-	-15	<td>	dB
η_D	drain efficiency	$P_{L(AV)} = 2.5\text{ W}$	<td>	13	-	%
ACPR	adjacent channel power ratio	$P_{L(AV)} = 2.5\text{ W}$	-	-47	<td>	dBc

8. Package outline

Flanged ceramic package; 2 mounting holes; 2 leads

SOT1135A

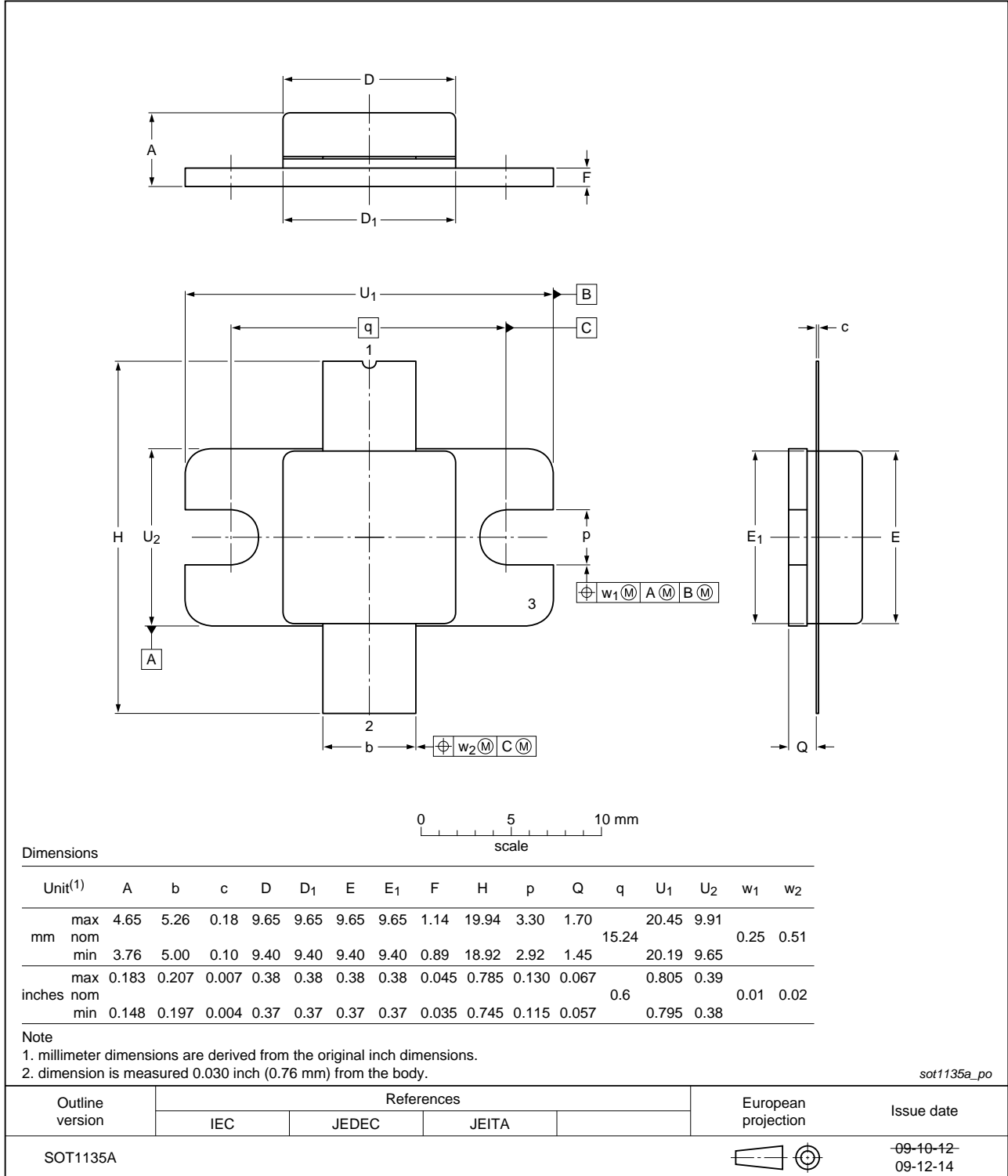
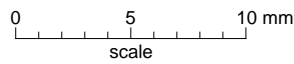
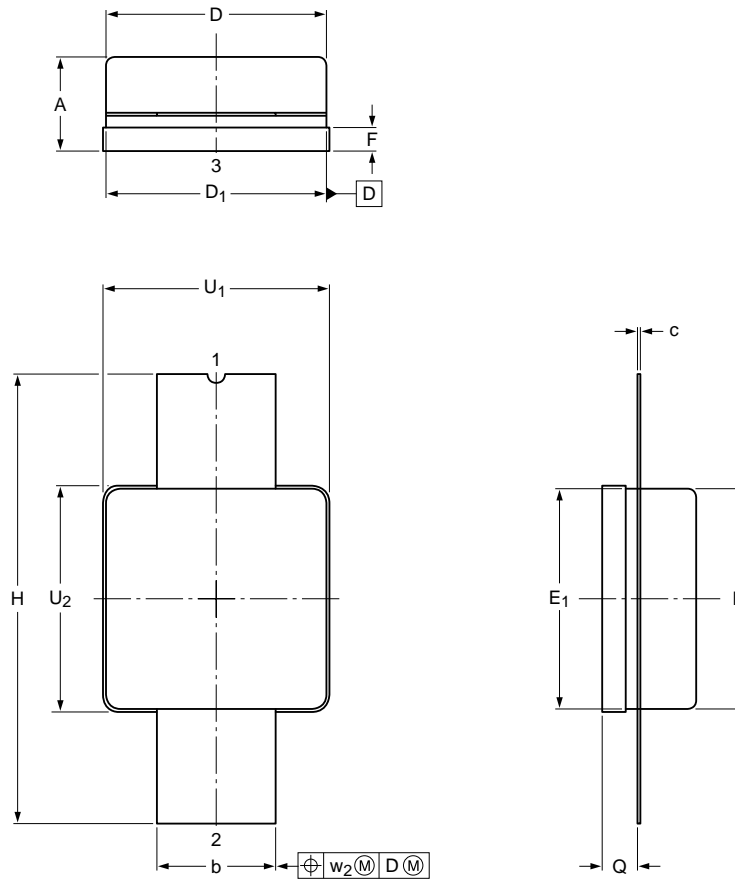


Fig 1. Package outline SOT1135A

Earless flanged ceramic package; 2 leads

SOT1135B



Dimensions

Unit ⁽¹⁾	A	b	c	D	D ₁	E	E ₁	F	H	Q	U ₁	U ₂	w ₂
mm	max	4.65	5.26	0.18	9.65	9.65	9.65	1.14	19.94	1.70	9.91	9.91	0.51
	nom												
	min	3.76	5.00	0.10	9.40	9.40	9.40	0.89	18.92	1.45	9.65	9.65	
inches	max	0.183	0.207	0.007	0.38	0.38	0.38	0.045	0.785	0.067	0.39	0.39	0.02
	nom												
	min	0.148	0.197	0.004	0.37	0.37	0.37	0.035	0.745	0.057	0.38	0.38	

Note

1. millimeter dimensions are derived from the original inch dimensions.
2. dimension is measured 0.030 inch (0.76 mm) from the body.

sot1135b_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1135B					-09-10-12- 09-12-14

Fig 2. Package outline SOT1135B

9. Handling information

CAUTION



This device is sensitive to ElectroStatic Discharge (ESD). Observe precautions for handling electrostatic sensitive devices.

Such precautions are described in the *ANSI/ESD S20.20*, *IEC/ST 61340-5*, *JESD625-A* or equivalent standards.

10. Abbreviations

Table 8. Abbreviations

Acronym	Description
3GPP	3rd Generation Partnership Project
CCDF	Complementary Cumulative Distribution Function
CW	Continuous Wave
LDMOS	Laterally Diffused Metal-Oxide Semiconductor
PAR	Peak-to-Average power Ratio
DPCH	Dedicated Physical Channel
RF	Radio Frequency
VSWR	Voltage Standing-Wave Ratio
W-CDMA	Wideband Code Division Multiple Access

11. Revision history

Table 9. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BLF6G15L-40RN_6G15LS-40RN v.1	20111027	Objective data sheet	-	-

12. Legal information

12.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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